ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1				Form Type Distribute										
Supplier	r Information													
Company	Company name*			Company unique ID			Unique ID Authority			Respon	Response Date*			
onsemi										2024-05-01				
Contact N	ame	Title - Contac	Title - Contact			Phone - Contact*			Email - Contact*					
Product-H	Env-Stewards		Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorize	d Representative*	Title - Repres	Title - Representative			Phone - Representative*			Email - Representative*					
Product-H	Env-Stewards		Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item Number		Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
		MT9P031I12STM-DP 5 MP 1/3 CIS				2024-05-01		TA1	259.		mg	Each		
Manufacturing Proccess Information														
	Terminal Plating / Grid Array Mate	Plating / Grid Array Material Terminal Base Alloy J-S		J-STD-020 MSI	L Rating	Rating Peak Process Body Temperature Max Time at Po			ak Temperature Number of Reflow Cycles					
	Precious metal (e.g. Ag,Au, NiPdASn)	Au) (no	CU Alloy 4		4		260	С	30	seco	nds 3			
Comments														
For more	information regarding material co	mposition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	59.5	mg		Misc.	proprietary data		0.2261	mg
			Supplier	Silicon (Si)	7440-21-3		58.6848	mg
			Supplier	Aluminum (Al)	7429-90-5		0.589	mg
Die Attach	2.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.825	mg
			Supplier	Ethylene Glycol	107-21-1		0.022	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.066	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.462	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.825	mg
Imaging Lens	55.3	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.765	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.765	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.765	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.765	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2765	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.765	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.765	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		38.4335	mg
Lid Attach	2.4	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.7584	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1248	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.7584	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.7584	mg
Mold Compound-Black	55.0	mg		Phenolic Resin	proprietary data		8.25	mg
			Supplier	Oxirane	39817-09-9		8.25	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.65	mg
			Supplier	Carbon Black (C)	1333-86-4		0.55	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.2	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1	mg
Substrate and Solder Mask	84.3	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		17.8632	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.1043	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2782	mg
			Supplier	Acetophenone Derivative	Proprietary Data		1.6523	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2782	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2782	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	8.194	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.3046	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	2.8325	mg
			Supplier	Copper (Cu)	7440-50-8	39.9666	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.548	mg
Wire Bond - Au	0.3	mg	Supplier	Gold (Au)	7440-57-5	0.3	mg